

AN3216

Multilayer Chip Antenna for 2.4GHz Wireless Communication



AN3216 Multilayer Chip Antenna

◆ Features

- Light weight and low profile 3.2mm(L)X1.6mm(W)X1.04mm(H)
- Omni-directional in azimuth
- Lead (Pb) Free

◆ Applications

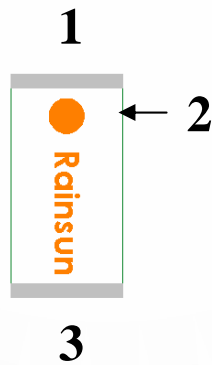
- 2.4GHz wireless communications
- 2.4GHz Modules
- Bluetooth System
- 802.11b/g Wireless LAN System

Specifications

Center frequency	2.45GHz
Peak gain	0.5dBi (typ.)
Operation temperature	-40 ~ +85 °C
Storage temperature	-40 ~ +85 °C
VSWR	2.5 (Max)
Input Impedance	50 Ohm
Power handling	1W (Max)
Bandwidth	110MHz (typ.)
Azimuth beamwidth	Omni-directional
Polarization	Linear
Soldering pad	Natural tin

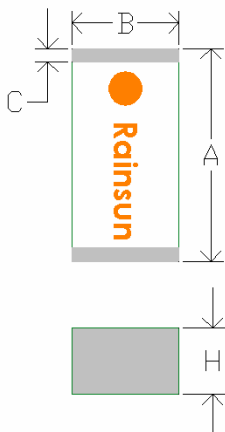
Pin configuration

Top view



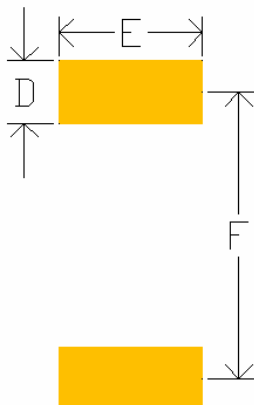
Pin No	Pin assignment
1	Feed termination
2	Feed point mark
3	Solder termination

Dimensions



Symbol	Dimensions(mm)
A	3.20 ± 0.10
B	1.60 ± 0.10
C	0.30 ± 0.05
H	1.04 ± 0.20

PCB Foot Print



Symbol	Dimensions(mm)
D	0.7
E	1.6
F	3.2

Recommended Test Board Pattern

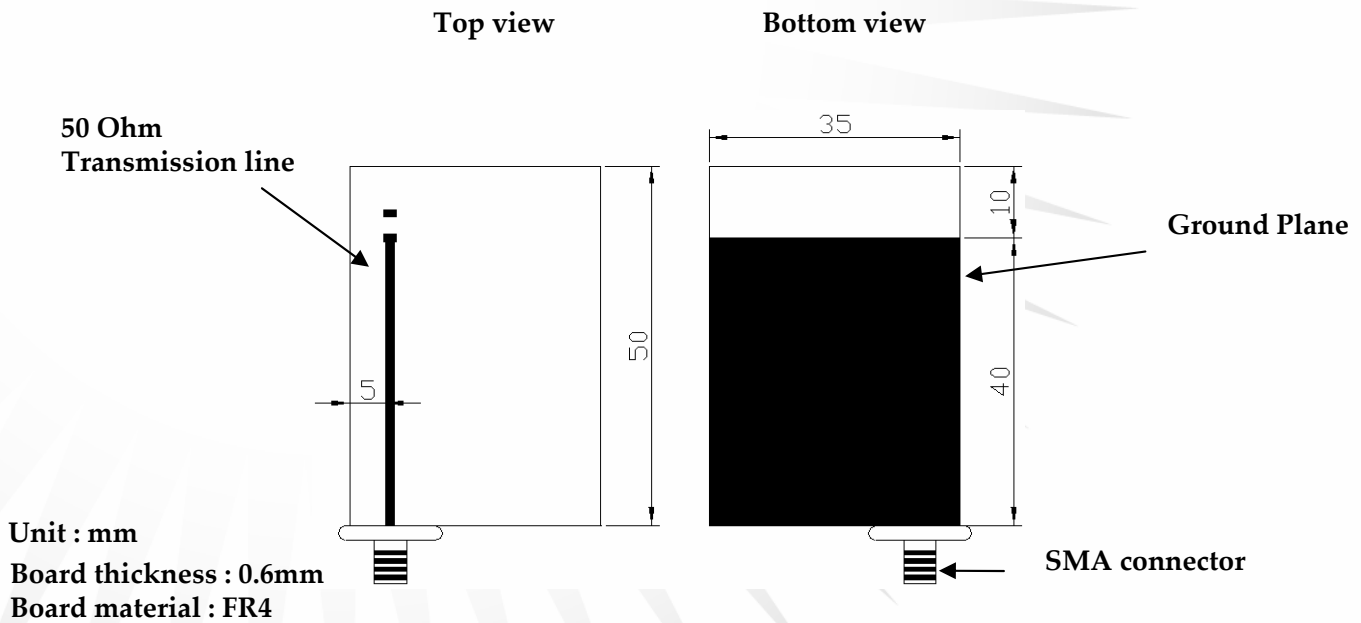
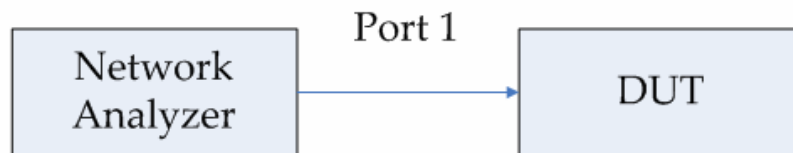


Fig-1

Testing Setup



Measurement



Testing Instrument:

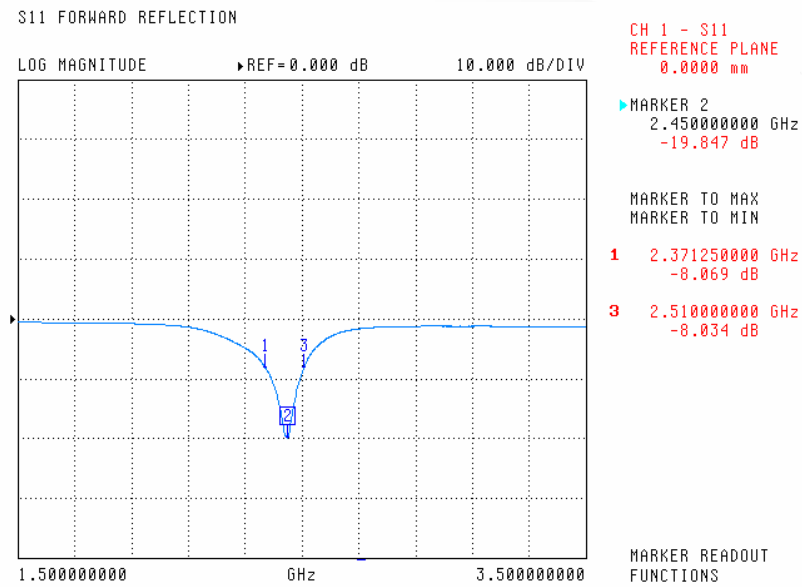
Anritsu 37369C VNA (Vector Network Analyzer)

VNA calibrate with 1 path reflection only calibration sequence on test board feed point.

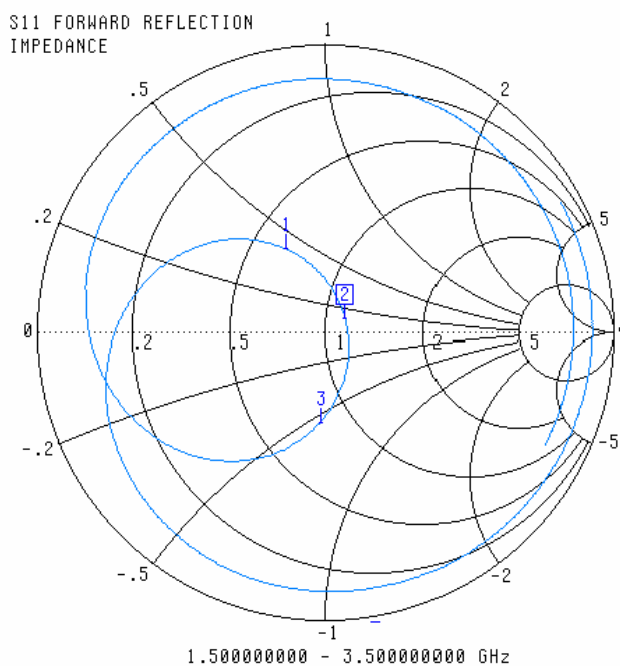
The test board dimension and its layout is the same as Fig-1.

Typical Electrical Characteristics

Return loss



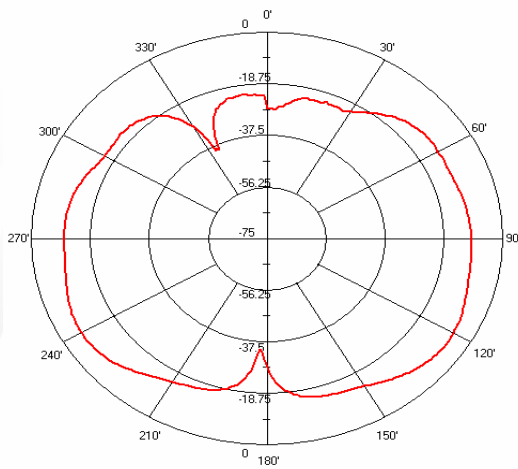
Smith Chart



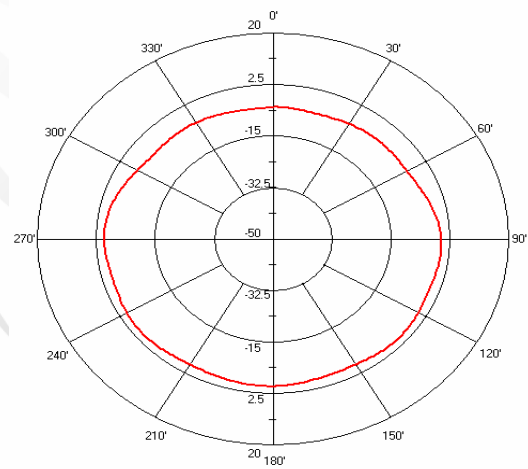
Marker data:
 1 : f=2.411 GHz
 2 : f=2.450 GHz
 3 : f=2.492 GHz

Typical Radiation Patterns

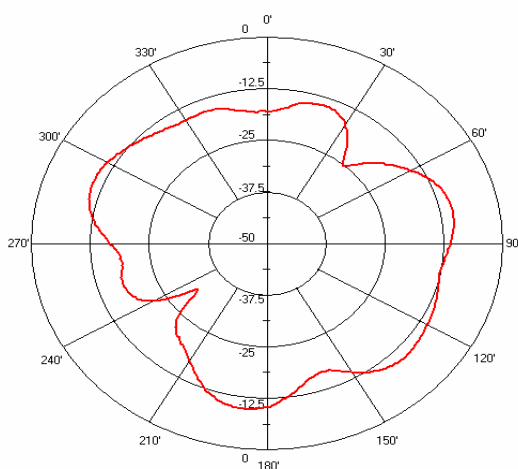
**2.45 GHz H-Plane
vertical**



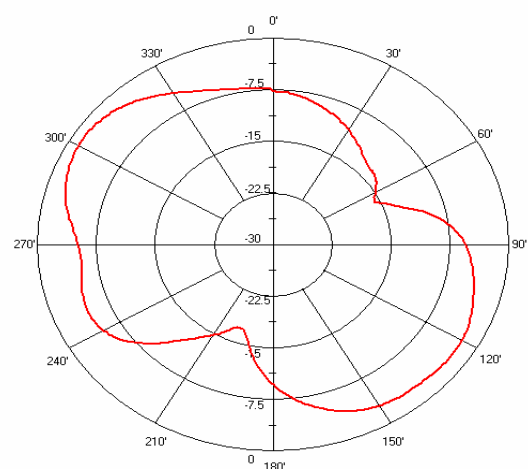
**2.45 GHz H-Plane
horizontal**



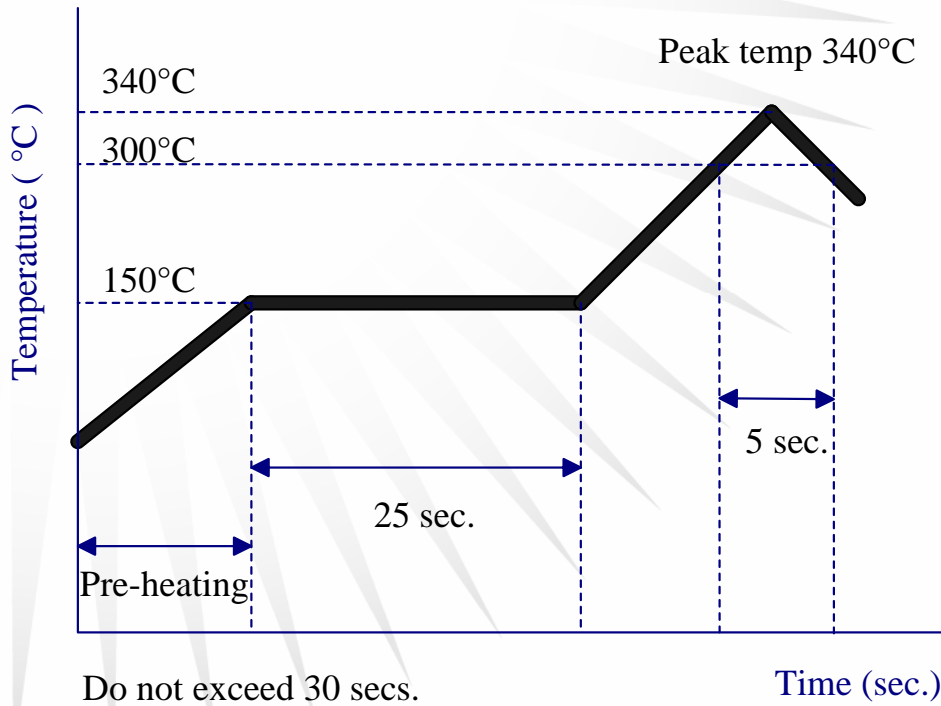
**2.45 GHz E-Plane
vertical**



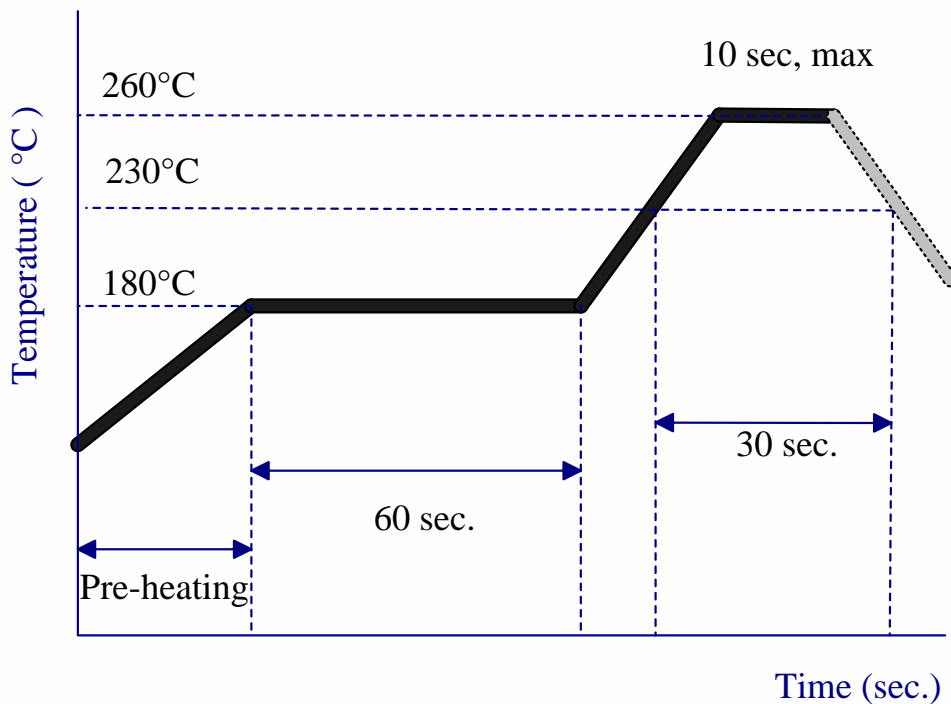
**2.45 GHz E-Plane
horizontal**



Typical Soldering Profile for Lead-free Process



Reflow Soldering



Application example

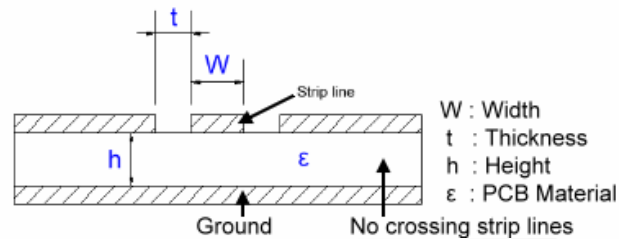
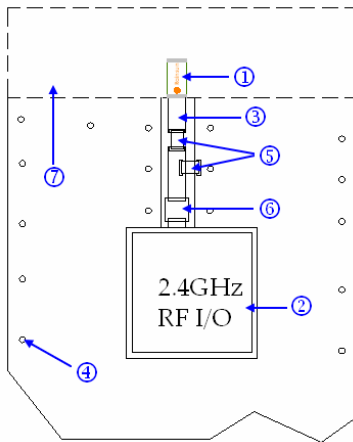
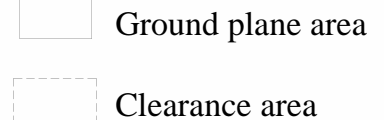
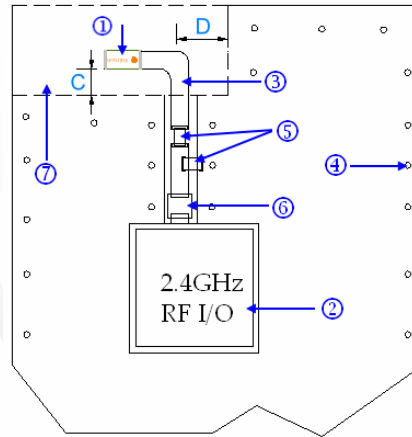


Fig.2

Best Choice



Acceptable



1. Placement of the antenna

The antenna shall be placed on a area without underlying ground plane at the edge of the PCB oriented as above. Ground plane area surrounding the antenna should be with minimum clearance 3mm.

2. Placement of 2.4 GHz module

To avoid losses in the strip line, the module shall be placed as close to the antenna as possible.

3. Strip line

The strip line impedance must be dimensioned according to your specific PCB (see fig.2) to 50 Ohm. No crossing strip lines are allowed between the strip line and its ground plane.

4. Via Connections on PCB

To avoid spurious effects via connections must be made to analogue ground. Via connection depends on PCB layout design. Figure 2 for reference only.

5. Component matching

Component values are depending on antenna placement, PCB dimensions and location of other components. PCB dimension and antenna location will effect the antenna frequency.

6. DC Block

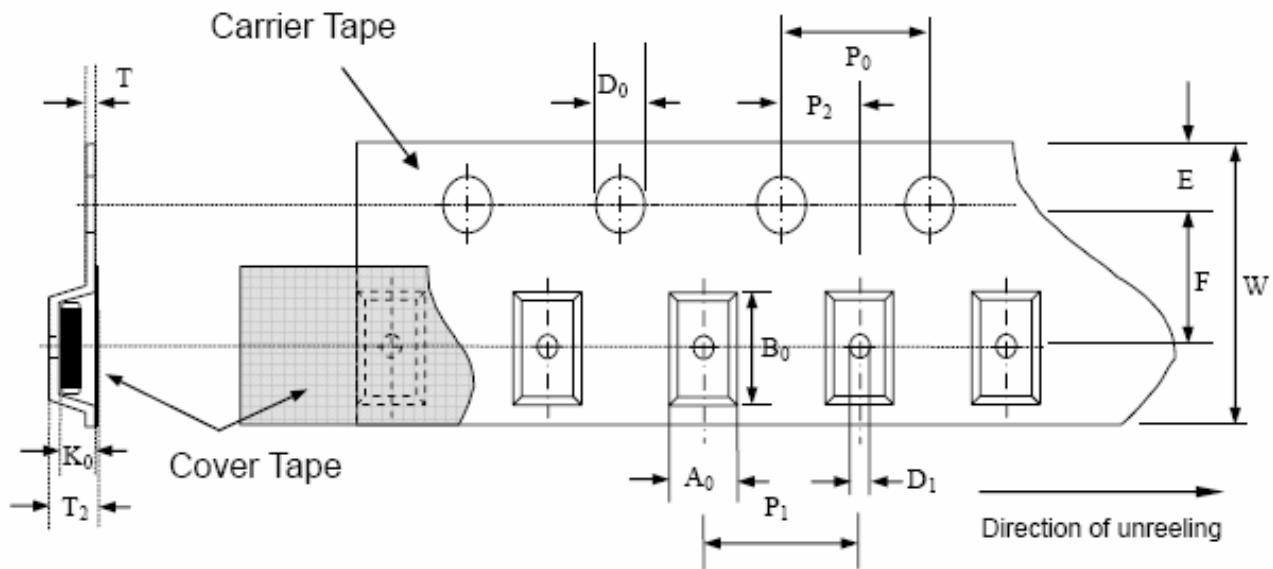
It might be needed depending on RF Module or chip hardware design.

7. Clearance

No components allowed within the clearance area with a minimum distance to other components. The minimum distance is 3mm.

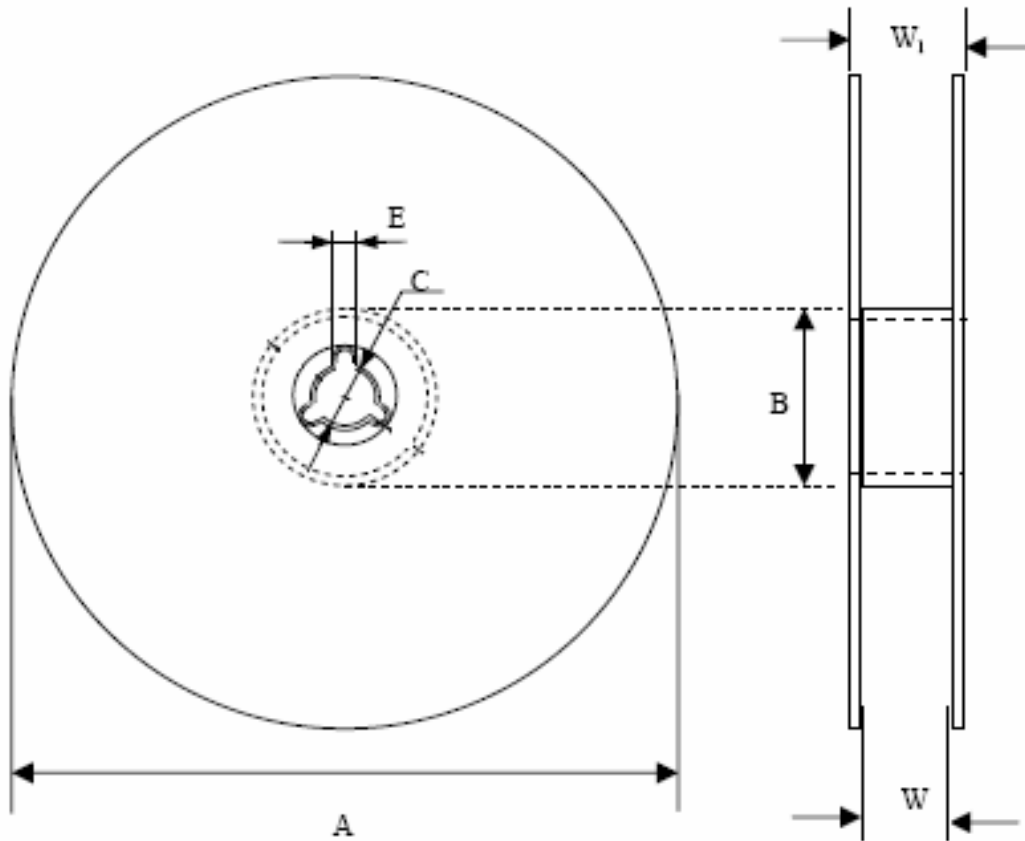
Packing

Blister Tape Specifications



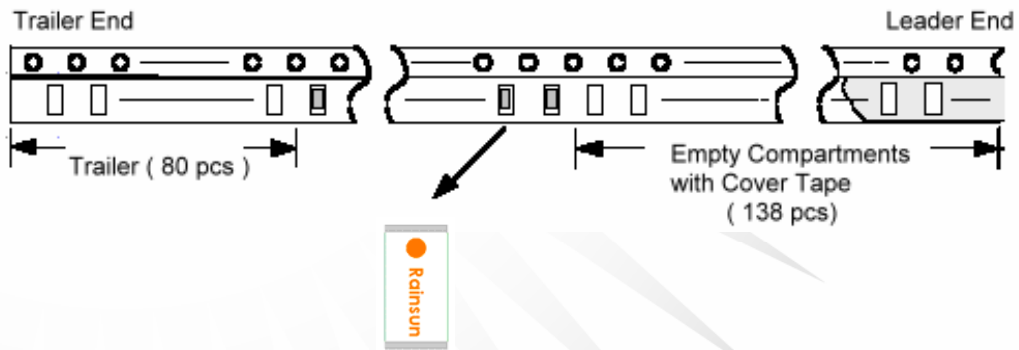
Symbol	Dimension	Tolerance	Unit
W	8.00	± 0.10	mm
E	1.75	± 0.10	mm
F	3.50	± 0.05	mm
D ₀	1.55	± 0.05	mm
D ₁	1.10	± 0.10	mm
P ₀	4.00	± 0.10	mm
P ₁	4.00	± 0.10	mm
P ₂	2.00	± 0.05	mm
A ₀	1.94	± 0.10	mm
B ₀	3.53	± 0.10	mm
K ₀	1.42	± 0.05	mm
T	0.23	± 0.01	mm
T ₂	>0.05	± 0.01	mm
10 × P ₀	40.00	± 0.20	mm

Reel Specifications

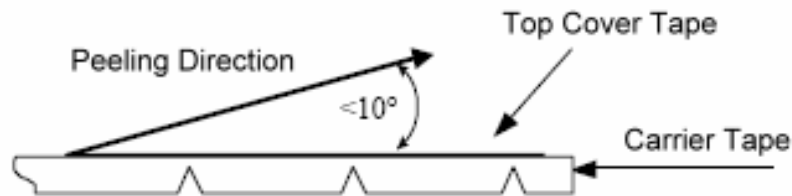


Quantity Per Reel	Tape Width (mm)	A (mm)	C (mm)	B (mm)	E (mm)	W (mm)	W ₁ (mm)
3,000	8	178±1	13±0.2	60±0.5	2.2±0.5	9±0.5	12±0.05

Tape Specifications



Tape Peel Strength



Peel-off force should be in the range of 0.1~0.6 N at a peel-off speed of 300 ± 10 mm/min.

Storage Conditions

- (1) Temperature : 15 to 35°C , Relative Humidity (RH) : 45 to 75%.
- (2) Non-corrosive environment.